

# Contents

- 1 Introduction** ..... 1
  - 1.1 Motivation and Context for Research ..... 1
  - 1.2 Objectives..... 3
  - 1.3 Research Contribution ..... 3
  - References..... 4
- 2 From Specifications to Concept** ..... 5
  - 2.1 Development Steps and Methodology..... 5
  - 2.2 Specifications for Consumer Applications ..... 6
  - 2.3 Choice of Transduction Principle..... 8
    - 2.3.1 Lorentz Force Transduction Principle ..... 8
    - 2.3.2 Position Sensing Techniques ..... 8
  - 2.4 State of the Art ..... 9
  - References..... 11
- 3 Lorentz Force Magnetometers** ..... 13
  - 3.1 Capacitive Readout MEMS ..... 13
    - 3.1.1 Dynamics of MEMS..... 13
    - 3.1.2 Electrostatic Forces: The Pull-in Phenomenon..... 17
  - 3.2 Z-axis Sensitive Magnetometer..... 21
  - 3.3 Mechanical Sensitivity at Fixed Resonance Frequency ..... 23
    - 3.3.1 Damping Modelling ..... 25
  - 3.4 Thermo-Mechanical Noise..... 27
    - 3.4.1 Intrinsic Resolution..... 27
  - References..... 28
- 4 System Design** ..... 31
  - 4.1 System Behavioral Model ..... 31
    - 4.1.1 Geometrical Data, Specifications, and Process Parameters ..... 33
    - 4.1.2 Damping Modelling ..... 33
    - 4.1.3 Mathematical Modelling of the Resonator ..... 33

4.1.4	Lorentz Force .....	35
4.1.5	System Model Outputs .....	35
4.2	Simulations Results and Devices Design .....	35
4.2.1	Sensitivity .....	36
4.2.2	Response Time.....	37
4.3	Noise Budget Partitioning .....	39
4.3.1	MEMS Noise .....	39
4.3.2	Electronics Noise .....	41
4.4	Power Budget Partitioning .....	41
	References.....	42
<b>5</b>	<b>Sensor Design and Fabrication.....</b>	<b>43</b>
5.1	FEM Simulations.....	43
5.2	Device Implementations and Layouts .....	44
5.2.1	Fabrication Process .....	46
	References.....	48
<b>6</b>	<b>A Custom Instrument for Electromechanical Characterization .....</b>	<b>49</b>
6.1	Motivations for a Custom Instrument .....	49
6.2	System Overview.....	51
6.2.1	Driving Electronics .....	52
6.2.2	Capacitive Readout Electronics .....	54
6.2.3	Data Acquisition and Display .....	58
6.3	Board Characterization: Noise and Sensitivity .....	58
6.4	Industrialization of the Instrument .....	63
	References.....	63
<b>7</b>	<b>Devices Electromechanical Characterization.....</b>	<b>65</b>
7.1	Time Domain Measurements .....	66
7.1.1	Stationary Device Characterization.....	66
7.1.2	Damping Measure and Experimental Proof of Presented Theory .....	68
7.2	Spectral Responses .....	70
	References.....	73
<b>8</b>	<b>Driving and Readout Electronics: A Discrete Components Solution .....</b>	<b>75</b>
8.1	Driving Electronics.....	75
8.1.1	Improved Howland Current Pump .....	77
8.1.2	A Solution for Differential Driving .....	81
8.1.3	PCB Realization and Tests .....	82
8.2	Capacitance Variations Readout .....	82
8.3	MEMS and Electronics Coupling: Parasitics Reduction .....	86
8.4	Transresistance Amplifier.....	87
8.4.1	Frequency Response .....	89
8.4.2	Noise Analysis .....	91
8.4.3	Differential to Single-Ended Conversion .....	93

8.5	Magnetic Field Measures .....	93
8.5.1	Experimental Setup .....	93
8.5.2	Sensitivity .....	95
8.5.3	Resolution .....	97
8.5.4	Influence of Possible Fluctuations of the Damping Coefficient .....	98
	References .....	100
<b>9</b>	<b>ASIC Design</b> .....	101
9.1	Architecture .....	101
9.2	A Continuous-Time Fully Differential Transresistance Amplifier .....	103
9.2.1	ASIC Noise .....	104
9.2.2	Fully Differential Operational Amplifier .....	108
9.3	Verilog—A Model for Cadence® Environment .....	111
9.3.1	MEMS MAIN Module .....	112
9.3.2	STOPPER Module .....	113
9.3.3	Simulations and Model Verification .....	115
9.4	Magnetic Field Measures: MEMS + ASIC .....	115
	References .....	119
<b>10</b>	<b>From Prototype to Product</b> .....	121
10.1	Towards Industrialization of MEMS Chip .....	121
10.1.1	Devices Redesign: The Second Generation of Magnetometers .....	121
10.1.2	Combination of Magnetometer with Other MEMS Sensors .....	122
10.1.3	Device Alternative Structures and Working Regimes.....	123
10.2	Towards Industrialization of ASIC Chip .....	124
	References .....	124
<b>11</b>	<b>Conclusions</b> .....	125
	<b>Index</b> .....	127

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